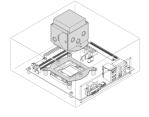


24830-002 INTERSCALE MOUNTING BRACKET FOR 70 MM FLEXIBLE HEAT CONDUCTOR (FHC), INTEL CPU





KEY FEATURES

Designed for ATX/ITX/Mini ITX & COM using Intel core-i processors and AMD processors with the following sockets: Intel: LGA775, LGA1150, LGA1155, LGA1156, LGA1366, LGA2011 ; AMD: AM2, AM2(+), AM3, AM3(+), FM1, FM2, FM2(+)

Utilizes keep out zones to not interfere with other board components

Designed to assemble the 70 mm Flexible Heat Conductor to thhe CPU

PRODUCT ATTRIBUTES

Product Type: Bracket

Product Family: Interscale

Type: CPU Adpater

Works With: Cases

Package Quantity: 1

ADDITIONAL PRODUCT DETAILS

The mounting bracket enables a user to assemble an Intel or AMD processor.



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